MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED







Description

The SRV05-4-P-T7 is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium.

Features

- IEC 61000-4-2 Level 4 ESD Protection
 - ±12kV Contact Discharge
 - ±17kV Air Discharge
- 60W Peak pulse Power (8/20us)
- Low clamping voltage
- Working voltage: 5V
- Low leakage current
- RoHS compliant
- Protecting 4 unidirectional lines
- Ultra-low capacitance: 0.6pF Typ.

Applications

- USB 2.0
- Monitors and flat panel displays
- 10/100/1000 ethernet
- Notebook computers
- SIM ports
- ATM interface

Reference News

Outline	Circuit Diagram	Marking
	$1 \circ 6 \circ 1 \circ 3 \circ 4$.V05
SOT-23-6		

Pin Configuration and Functions

Pin	Name	Description	Pin	Name	Description
1	IO1	Connect to I/O	4	IO3	Connect to I/O
2	GND	Connect to GND	5	Vcc	Connect to Vcc
3	IO2	Connect to I/O	6	104	Connect to I/O



Absolute Maximum rating

Over operating free-air temperature range (unless otherwise noted)

Parameters	Symbol	Min.	Max.	Unit
Peak pulse power (tp=8/20us)@25°C	P _{pk}	-	60	W
Peak pulse current (tp=8/20us)@25°C	I _{PP}		4.5	А
ESD (IEC61000-4-2 air discharge) @25°C	Vesd	-	±17	kV
ESD (IEC61000-4-2 contact discharge) @25°C	Vesd	-	±12	kV
Junction temperature	TJ	-	150	°C
Operating temperature	T _{OP}	-40	125	°C
Storage temperature	Tstg	-55	150	°C
Lead temperature	T∟	-	260	°C

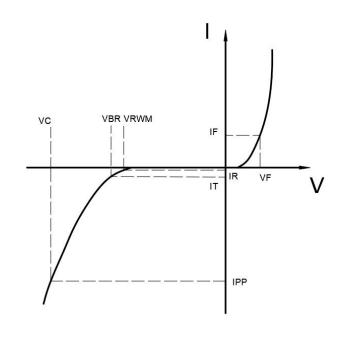
Electrical Characteristics

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Reverse Stand-off Voltage	V _{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	IT=1mA	6			V
Reverse Leakage Current	I _R	V _{RWM} =5V			1	uA
Clamping Voltage	Vc	I _{PP} =1A; tp=8/20us		9		V
Clamping Voltage	Vc	I _{PP} =4.5A; tp=8/20us		12		V
Junction Capacitance	C	I/O to GND; VR=0V; f=1MHz		0.6	0.8	pF
	U J	Between I/O; VR=0V; f=1MHz		0.3	0.4	pF

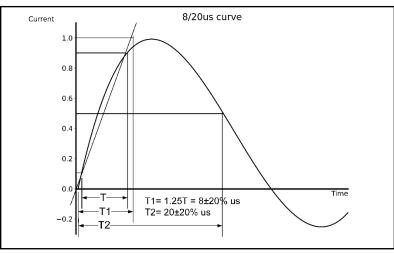
MSKSEMI SEMICONDUCTOR

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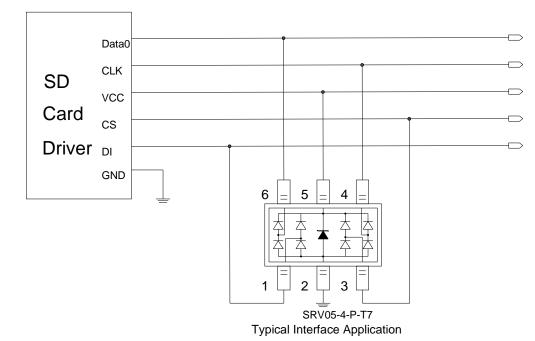
Symbol	Parameters	
V _{RWM}	Peak Reverse Working Voltage	
R	Reverse Leakage Current @ V _{RWM}	
V _{BR}	Breakdown Voltage @ I⊤	
ћ	Test Current	
IPP	Maximum Reverse Peak Pulse Current	
Vc	Clamping Voltage @ IPP	
lF	Forward Current	
VF	Forward Voltage @ I _F	



Typical Characteristic

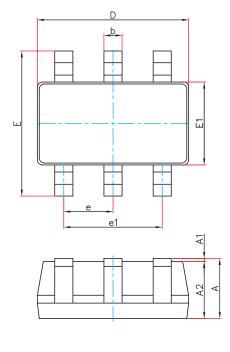


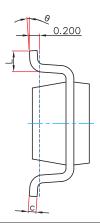
Typical Application





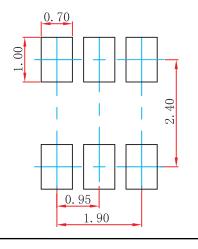
SOT-23-6 Package Outline Dimensions





Symbol	Dimensions In	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037((BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	
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SOT-23-6 Suggested Pad Layout



Note:

1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SRV05-4-P-T7	SOT-23-6	3000



SRV05-4-P-T7

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